

Device Selection Guide

Chip Type	Chip Materials	Emitted Color	Resin Color	
SUR	AlGaInP	Brilliant Red	Water Clear	
SYG	AlGaInP	Brilliant Yellow Green	Water Clear	

Absolute Maximum Ratings (Ta=25℃)

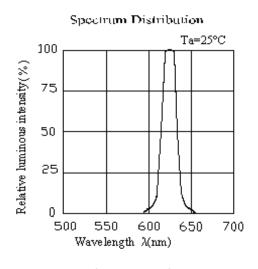
Parameter	Symbol	Rating	Unit	
Reverse Voltage	V_R	5	V	
Forward Current	1	SUR: 25	m A	
Forward Current	I _F	SYG: 25	mA	
Peak Forward Current	1	SUR : 60	^	
(Duty 1/10 @1KHz)	I _{FP}	SYG: 60	mA	
Davis Dissination	DJ	SUR: 60		
Power Dissipation	Pd	SYG: 60	mW	
Operating Temperature	T _{opr}	-40 ~ +85	$^{\circ}$ C	
Storage Temperature	Tstg	-40 ~ +90	${\mathbb C}$	
Electroptotic Discharge	TCD.	SUR: 2000	V	
Electrostatic Discharge	ESD_HBM	SYG: 2000	V	
Caldarina Tamanaratura	T _{sol}	Reflow Soldering : 260 °C for 10 sec.		
Soldering Temperature		Hand Soldering : 350 °C for 3 sec.		

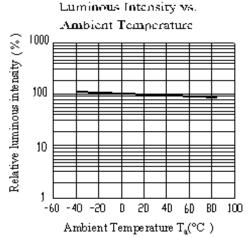
Electro-Optical Characteristics (Ta=25°℃)

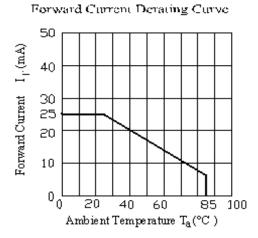
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	SUR : 21.0	51.0		mcd	
Lammous interiors,	• • • • • • • • • • • • • • • • • • • •	SYG: 14.0	21.0			
Viewing Angle	2θ _{1/2}		60		deg	
Deal Maralanath	۱	SUR :	632		nm	I _F =20mA
Peak Wavelength	λр	SYG:	575			
Deminant Weyelen oth	۱ ، ا	SUR:	624		nm	
Dominant Wavelength	λd	SYG:	573			
Construes Dodiction Donaturiath	^ 1	SUR :	20		nm	
Spectrum Radiation Bandwidth	$\triangle \lambda$	SYG:	20			
Famurand Valtages	\ /	SUR: 1.70	2.00	2.40	V	
Forward Voltage	V_{F}	SYG: 1.70	2.00	2.40		
Davida Comment	I _R	SUR :		10	μΑ	V _R =5V
Reverse Current		SYG:		10		

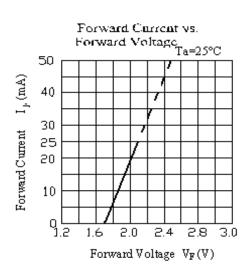


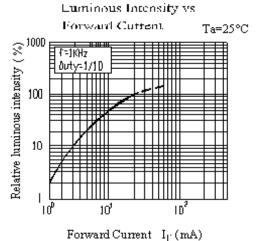
Typical Electro-Optical Characteristics Curves SUR

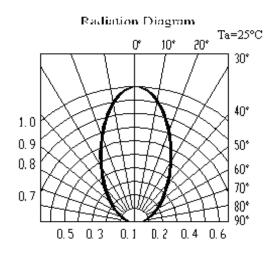




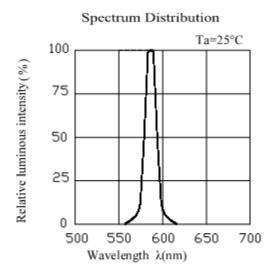


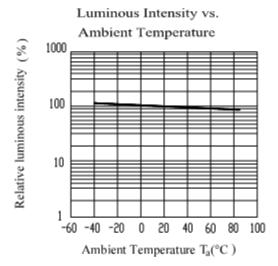


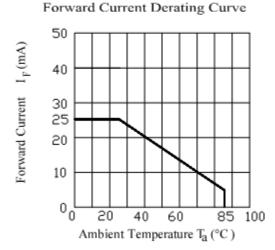


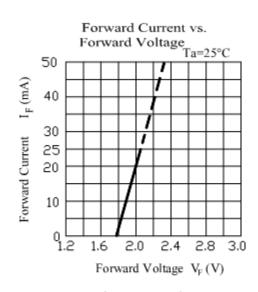


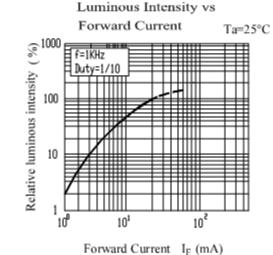
Typical Electro-Optical Characteristics Curves SYG

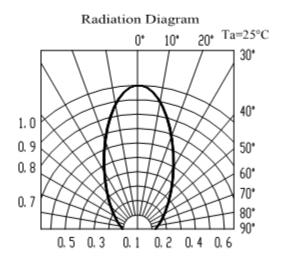




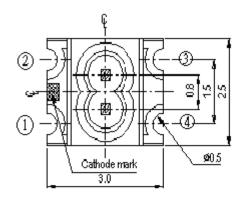


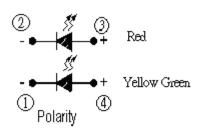


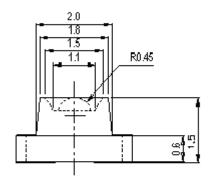




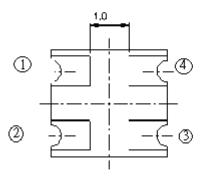
Package Outline Dimensions

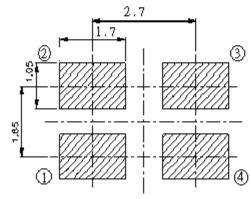






For reflow soldering (propose)





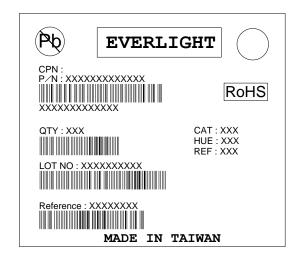
Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm



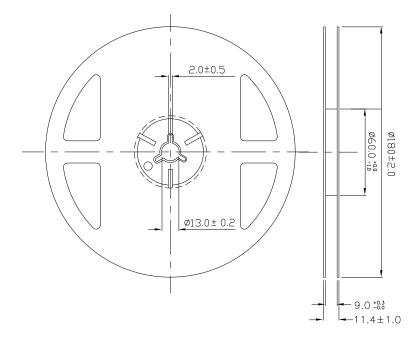
Moisture Resistant Packing Materials

Label Explanation



- · CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

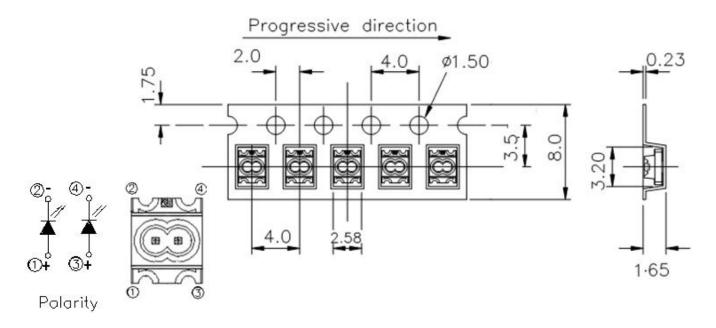
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

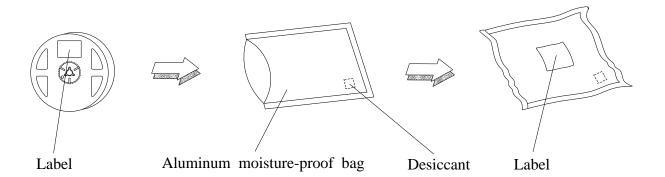


Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Moisture Resistant Packaging





Precautions For Use

1. Over-current-proof

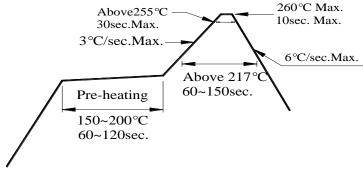
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 After opening the package: The LEDs should be kept at 30°℃ or less and 60%RH or less.
- 2.3 The LEDs should be used within 168 hours (7days) after opening the package . If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours

- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



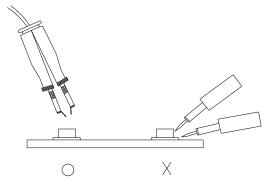
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.